



# **SEMICONDUCTOR PACKAGING DEVICE AND MANUFACTURE THEREOF**

5

## **BACKGROUND OF THE INVENTION**

### **1. Field of the Invention**

The invention relates to a stacking semiconductor packaging  
10 device and manufacture thereof, and more particularly relates to a  
structure of flip chip ball grid array (FCBGA) and manufacture thereof.

### **2. Description of the Prior Art**

15

In packaging manufacture, especially in packaging  
manufacture of FCBGA for integrated circuits (ICs) of high-density I/O  
or few I/O on small area, the bonding pads on ICs need to be  
rearranged for an array by a redistribution process, followed by the  
20 formation of under-bumping-metallization layer and solder bumps.  
Due to the limitation of general print circuit board (PCB) on the  
high-density I/O layout of integrated circuits, a flip chip is first affixed  
to a build-up substrate, followed by fanning-out the I/O pins of the flip  
chip to become great-pitch-distribution area.

25

However, due to the small solder bumps on the flip chips and

the difference of thermal expansion between the solder bumps and the BT substrate, it is necessary to fill the gaps among the flip chip, solder bumps, and a general substrate with underfilled gel on consideration of reliability. Thus, the consumptions of time and cost for such a process are high.

### **SUMMARY OF THE INVENTION**

It is one object of the present invention to provide a semiconductor packaging and manufacture thereof. An additionally high-cost fan-out process and thereto relative steps are not necessary for the present invention.

improved structure of FCBGA and manufacture thereof. The redistribution and solder-bump process for a conventional structure of FCBGA are simplified and integrated into the fan-out process of build-up substrate.

It is further object of the present invention to provide a novel packaging structure with improved reliability and manufacture thereof. A chip is prevented from affixing to a PCB directly such that a thickness of the novel packing structure is minimum and met with the requirement of heat radiation.

In the present invention, a semiconductor packaging device

comprises a carrier having at least a cavity or a slot thereon. At least a chip has a back surface and an active surface with a plurality of first bonding pads. The chip is affixed to the cavity to expose the active surface. A first insulating layer is on the active surface and the carrier, which comprises first plating through holes connected to first bonding pads and via the first insulating layer. A multi-layer structure is on the first insulating layer, which comprises conductive layout lines, second plating through holes therein, and a second insulating layer and exposed ball pads thereon. The first plating through holes are electrically connected with the conductive layout lines, the second plating through holes, and the exposed ball pads. A plurality of solder balls are affixed to the ball pads. Such architecture integrates the redistribution and fan-out process, which simplifies the conventional process for flip-chip ball grid array.

### **BRIEF DESCRIPTION OF THE DRAWINGS**

A better understanding of the invention may be derived by reading the following detailed description with reference to the accompanying drawings wherein :

FIG.1 is a flow chart illustrating the manufacture process in accordance with the present invention;

FIG.2 is a plane view illustrating the arrangement of the chips

and the carrier in accordance with the present invention;

FIG.3 is a cross-sectional schematic diagram illustrating the packaging chip cut with line 2A-2A in FIG. 2;

5

FIG.4 is a cross-sectional schematic diagrams illustrating the packaging chip cut with line 2A-2A in FIG. 2;

FIG.5 is a cross-sectional schematic diagram illustrating the packaging chip cut with line 2A-2A in FIG. 2;

10

FIG.6 is a cross-sectional schematic diagram illustrating the packaging chip cut with line 2A-2A in FIG. 2; and

15

FIG.7 is a cross-sectional schematic diagram illustrating the packaging chip cut with line 3A-3A in FIG. 2.

#### **DESCRIPTION OF THE PREFERRED EMBODIMENT**

20

While the invention is described in terms of a single preferred embodiment, those skilled in the art will recognize that many devices described below can be altered as well as other substitutions with same function and can be freely made without departing from the spirit and scope of the invention.

25

Furthermore, there is shown a representative portion of semiconductor packaging of the present invention in enlarged. The drawings are not necessarily to scale for clarify of illustration and should not be interpreted in a limiting sense. Furthermore, the present invention can be applied on various multichip devices or packages.

In the present invention, a semiconductor packaging device comprises a carrier having at least a cavity or a slot thereon. At least a chip has a back surface and an active surface with a plurality of first bonding pads. The chip is affixed to the cavity to expose the active surface. A first insulating layer is on the active surface and the carrier, which comprises first plating through holes connected to first bonding pads and via the first insulating layer. A multi-layer structure is on the first insulating layer, which comprises conductive layout lines, second plating through holes therein, and a second insulating layer and exposed ball pads thereon. The first plating through holes are electrically connected with the conductive layout lines, the second plating through holes, and the exposed ball pads. A plurality of solder balls are affixed to the ball pads. Such architecture integrates the redistribution and fan-out process, which simplifies the conventional process for flip-chip ball grid array.

FIG. 1 is a flow chart illustrating the manufacture process in

accordance with the present invention. One embodiment of the present invention is a manufacture process of FCBGA. A wafer is first grinded and the dies (chips) on the grinded wafer are sawed (step 50). The chips are attached to a carrier having multitudes of cavities or slots (step 51), wherein the active surfaces of the chips are faced upwards and the back surfaces/sidewalls of the chips are affixed to the cavities with adhesive. Furthermore, the carrier can be made of silicon, ceramic, glass, or organic substrate, and so on. Next, an insulating layer is coated on the active surfaces of the chips and the surface of the carrier, and thereafter multitudes of bonding pads on the surroundings of the active surfaces are exposed (step 52). The coating of the insulating layer can be implemented by conventional process of semiconductor film. And the insulating layer provides protection and planarization for the chips and the carrier. Furthermore, multitudes of first conductive via holes (plating through holes) are made in the insulating layer (step 53), wherein the first conductive holes are located corresponding to the bonding pads on the chip.

A layout for second conductive via holes and a multi-layer circuit are implemented on the insulating layer (step 54). The multi-layer circuit connects electrically the first via holes with the second via holes. Next, the re-distribution is implemented (step 55), wherein those re-distributed bonding pads are located corresponding to the second conductive via holes and aligned to a great-pitch array

on a substrate. It can be implemented by conventional redistribution process and the process of under bump metallization. That is, a single/multi-layer film with predetermined circuit and plating through holes is used to adhere to the adhesive on the chips and the carrier, wherein the plating through holes are connected to the bonding pads of the chip. Then another adhesive is coated on the single/multi-layer film and the pads of the plating through holes are exposed. Next, the packaging chips are grinded and sawed followed by attaching multitudes of solder balls to the predetermined location (the locations of re-distributed pads and the second via holes) and reflow (step 56). The attachment of the solder balls can be implemented by conventional methods for ball grid array. Furthermore, the chips and the carriers can be grinded to a predetermined packaging thickness.

FIG. 2 is a plane view illustrating the arrangement of the chips and the carrier in accordance with the present invention. Depicted in FIG. 2, there are multitudes of cavities 10 (or slots) on the carrier 11, in which each one is fitted for one chip. The back surfaces of the chips are affixed to the bottoms of the cavities with adhesive, as well as the sidewalls of the chips to the sidewalls of the cavities.

FIGS. 3-5 are cross-sectional views illustrating the packaging chip cut with line 2A-2A of FIG. 2. Depicted in FIG. 3, solder balls are distributed on the surrounding of the chip. After the chip 20 is placed

in the carrier 11 and affixed by an adhesive 19, an insulating layer 14 is formed on the active surface 30 of the chip 20 and the carrier 11 where the bonding pads 21 of the chip 20 are exposed. A multi-layer film 15 with predetermined circuit 23 and plating through holes 22 is on the insulating layer 14 and thereafter another insulating layer 16 is formed on the multi-layer film 15 only to expose the pads 18 of the plating through holes 22 on which the solder balls 17 are affixed, and the solder balls are distributed on the carrier 11, the chip 20, or both. Thus, the pad redistribution, bumping, and fan-out processes for the chips can be implemented at one time. One of advantages of the present invention is to avoid the direct chip attachment to a print circuit board for fear of poor reliability. Furthermore, the packaging thickness is minimum and the heat radiation is improved.

Shown in FIG.4 similar to FIG. 3, the thickness of a carrier 13 is almost equal to one of the chip 20 such that the back surface 31 of the chip 20 is exposed and only the sidewall of the chip 20 is affixed to the carrier 13.

Depicted 5, in addition to the back surface 31 of the chip 20 in the cavity of the carrier 13, the carrier 13 could comprise predetermined circuit layout 26, and solder pads 24 (exposed by an insulating layer 25), when the carrier 13 is made of organic material. The active surface 30 of the chip 20 is connected electrically to the



conductive via predetermined circuit 26 of the carrier 13 through the circuit layout 23 of the multi-layer film 15 and the plating through holes 22 in the insulating layer 14. Multitudes of solder balls 17 are affixed to the solder pads 24 of the carrier 13.

5

FIG. 6 is a cross-sectional view illustrating the packaging chip cut with line 2A-2A in FIG.2. Beside of the equal thickness of the chip 20 and the carrier 13, the carrier 13 is made of an organic material so as to have the predetermined circuit 26 therein and solder pads 24 thereon. The active surface 30 of the chip 20 are connected to the solder pads 24 of the carrier 13 through the multi-layer film 15. The solder balls 17 are affixed to the solder pads 24 on the carrier 13 surrounding the back surface 31 of the chip.

15

FIG. 7 is a cross-sectional view illustrating the packaging chip cut with line 3A-3A in FIG. 2. In this embodiment, the thickness of the carrier 11 is equal to that of the chip 20. Two chips 20 are affixed to the sidewall of the carrier 11 with their individual sidewall, and exposed their individual back surface 31 out. One of advantages in the embodiment, the two chips 20 can have electric interconnection through the multi-layer film 15 with its predetermined circuit. To be specific, the carrier 11 in the embodiment is also made of the organic material that can have predetermined layout. The solder balls 17 are distributed on the carrier 11 that is at the same side with the back

surface 31 of the chip 20.

While this invention has been described with reference to illustrative embodiments, this description is not intended to be  
5 construed in a limiting sense. Various modifications and combinations of the illustrative embodiments, as well as other embodiments of the invention, will be apparent to persons skilled in the art upon reference to the description. It is therefore intended that the appended claims encompass any such modifications or  
10 embodiments.